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What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	ARM® Cortex®-M4
Core Size	32-Bit Single-Core
Speed	120MHz
Connectivity	CANbus, I²C, SPI, UART/USART, USB OTG
Peripherals	Brown-out Detect/Reset, DMA, I²S, LVD, POR, PWM, WDT
Number of I/O	66
Program Memory Size	128KB (128K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	64K x 8
Voltage - Supply (Vcc/Vdd)	1.71V ~ 3.6V
Data Converters	A/D 1x16b; D/A 1x12b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 105°C (TA)
Mounting Type	Surface Mount
Package / Case	100-LQFP
Supplier Device Package	100-LQFP (14x14)
Purchase URL	https://www.e-xfl.com/product-detail/nxp-semiconductors/mks22fn128vll12

2.1 System features

The following sections describe the high-level system features.

2.1.1 ARM Cortex-M4 core

The ARM Cortex-M4 is the member of the Cortex M Series of processors targeting microcontroller cores focused on very cost sensitive, deterministic, interrupt driven environments. The Cortex M4 processor is based on the ARMv7 Architecture and Thumb®-2 ISA and is upward compatible with the Cortex M3, Cortex M1, and Cortex M0 architectures. Cortex M4 improvements include an ARMv7 Thumb-2 DSP (ported from the ARMv7-A/R profile architectures) providing 32-bit instructions with SIMD (single instruction multiple data) DSP style multiply-accumulates and saturating arithmetic.

2.1.2 NVIC

The Nested Vectored Interrupt Controller supports nested interrupts and 16 priority levels for interrupts. In the NVIC, each source in the IPR registers contains 4 bits. It also differs in number of interrupt sources and supports 240 interrupt vectors.

The Cortex-M family uses a number of methods to improve interrupt latency . It also can be used to wake the MCU core from Wait and VLPW modes.

2.1.3 AWIC

The asynchronous wake-up interrupt controller (AWIC) is used to detect asynchronous wake-up events in Stop mode and signal to clock control logic to resume system clocking. After clock restarts, the NVIC observes the pending interrupt and performs the normal interrupt or event processing. The AWIC can be used to wake MCU core from Partial Stop, Stop and VLPS modes.

The security circuitry prevents unauthorized access to RAM or flash contents from debug port.

- System register file

  This device contains a 32-byte register file that is powered in all power modes.

  Also, it retains contents during low power modes and is reset only during a power-on reset.

2.1.5 Reset and boot

The following table lists all the reset sources supported by this device.

NOTE

In the following table, Y means the specific module, except for the registers, bits or conditions mentioned in the footnote, is reset by the corresponding Reset source. N means the specific module is not reset by the corresponding Reset source.

Table 3. Reset source

Reset sources	Descriptions	Modules								
		PMC	SIM	SMC	RCM	LLWU	Reset pin is negated	RTC	LPTMR	Others
POR reset	Power-on reset (POR)	Y	Y	Y	Y	Y	Y	Y	Y	Y
System resets	Low-voltage detect (LVD)	Y[1]	Y	Y	Y	Y	Y	N	Y	Y
	Low leakage wakeup (LLWU) reset	N	Y[2]	N	Y	N	Y[3]	N	N	Y
	External pin reset ($\overline{\text{RESET}}$)	Y[1]	Y[2]	Y[4]	Y	Y	Y	N	N	Y
	Watchdog (WDOG) reset	Y[1]	Y[2]	Y[4]	Y[5]	Y	Y	N	N	Y
	Multipurpose clock generator loss of clock (LOC) reset	Y[1]	Y[2]	Y[4]	Y[5]	Y	Y	N	N	Y
	Multipurpose clock generator loss of lock (LOL) reset	Y[1]	Y[2]	Y[4]	Y[5]	Y	Y	N	N	Y
	Stop mode acknowledge error (SACKERR)	Y[1]	Y[2]	Y[4]	Y[5]	Y	Y	N	N	Y
	Software reset (SW)	Y[1]	Y[2]	Y[4]	Y[5]	Y	Y	N	N	Y
	Lockup reset (LOCKUP)	Y[1]	Y[2]	Y[4]	Y[5]	Y	Y	N	N	Y

Table continues on the next page...

Table 3. Reset source (continued)

Reset sources	Descriptions	Modules								
		PMC	SIM	SMC	RCM	LLWU	Reset pin is negated	RTC	LPTMR	Others
	MDM DAP system reset	Y[1]	Y[2]	Y[4]	Y[5]	Y	Y	N	N	Y
Debug reset	Debug reset	Y[1]	Y[2]	Y[4]	Y[5]	Y	Y	N	N	Y

1. Except PMC_LVDSC1[LVDV] and PMC_LVDSC2[LVWV]
2. Except SIM_SOPT1
3. Only if $\overline{\text{RESET}}$ is used to wake from VLLS mode.
4. Except SMC_PMCTRL, SMC_STOPCTRL, SMC_PMSTAT
5. Except RCM_RPFC, RCM_RPFW, RCM_FM

This device supports booting from:

- internal flash

2.1.6 Clock options

The MCG module controls which clock source is used to derive the system clocks. The clock generation logic divides the selected clock source into a variety of clock domains, including the clocks for the system bus masters, system bus slaves, and flash memory . The clock generation logic also implements module-specific clock gating to allow granular shutoff of modules.

The primary clocks for the system are generated from the MCGOUTCLK clock. The clock generation circuitry provides several clock dividers that allow different portions of the device to be clocked at different frequencies. This allows for trade-offs between performance and power dissipation.

Various modules, such as the USB OTG Controller, have module-specific clocks that can be generated from the IRC48MCLK or MCGPLLCLK or MCGFLLCLK clock. In addition, there are various other module-specific clocks that have other alternate sources. Clock selection for most modules is controlled by the SOPT registers in the SIM module.

For more details on the clock operations and configurations, see the Clock Distribution chapter in the Reference Manual.

The following figure is a high level block diagram of the clock generation.

2.2.1 eDMA and DMAMUX

The eDMA is a highly programmable data-transfer engine optimized to minimize any required intervention from the host processor. It is intended for use in applications where the data size to be transferred is statically known and not defined within the transferred data itself. The DMA controller in this device implements 16 channels which can be routed from up to 63 DMA request sources through DMA MUX module.

Main features of eDMA are listed below:

- All data movement via dual-address transfers: read from source, write to destination
- 16-channel implementation that performs complex data transfers with minimal intervention from a host processor
- Transfer control descriptor (TCD) organized to support two-deep, nested transfer operations
- Channel activation via one of three methods
- Fixed-priority and round-robin channel arbitration
- Channel completion reported via programmable interrupt requests
- Programmable support for scatter/gather DMA processing
- Support for complex data structures

2.2.2 TPM

This device contains three low power Timer/PWM Modules (TPM), one with 6 channels and the other two with 2 channels. All TPM modules are functional in Stop/ VLPS mode if the clock source is enabled.

The TPM features are as follows:

- TPM clock mode is selectable (can increment on every edge of the asynchronous counter clock, or only on on rising edge of an external clock input synchronized to the asynchronous counter clock)
- Prescaler divide-by 1, 2, 4, 8, 16, 32, 64, or 128
- Include a 16-bit counter
- Include 6 or 2 channels (1×6ch, 2×2ch) that can be configured for input capture, output compare, edge-aligned PWM mode, or center-aligned PWM mode
- Support the generation of an interrupt and/or DMA request per channel or counter overflow

- Selectable priority between mailboxes and Rx FIFO during matching process
- Powerful Rx FIFO ID filtering, capable of matching incoming IDs against either 128 extended, 256 standard, or 512 partial (8 bit) IDs, with up to 32 individual masking capability

2.2.15 LPI2C

This device contains two LPI2C modules. The LPI2C is a low power Inter-Integrated Circuit (I2C) module that supports an efficient interface to an I2C bus as a master and/or a slave. The LPI2C can continue operating in stop modes provided an appropriate clock is available and is designed for low CPU overhead with DMA offloading of FIFO register accesses. The LPI2C implements logic support for standard-mode, fast-mode, fast-mode plus and ultra-fast modes of operation. The LPI2C module also complies with the *System Management Bus (SMBus) Specification, version 2*.

The LPI2C modules have the following features:

- Standard, Fast, Fast+ and Ultra Fast modes are supported
- HS-mode supported in slave mode
- Multi-master support including synchronization and arbitration
- Clock stretching
- General call, 7-bit and 10-bit addressing
- Software reset, START byte and Device ID require software support
- For master mode:
  - command/transmit FIFO of 4 words
  - receive FIFO of 4 words
- For slave mode:
  - separate I2C slave registers to minimize software overhead due to master/slave switching
  - support for 7-bit or 10-bit addressing, address range, SMBus alert and general call address
  - transmit/receive data register supporting interrupt or DMA requests

2.2.16 USB

This device contains one USB module which implements a USB2.0 full-speed compliant peripheral and interfaces to the on-chip USBFS transceiver. It enables IRC48M to allow crystal-less USB operation.

The USBFS has the following features:

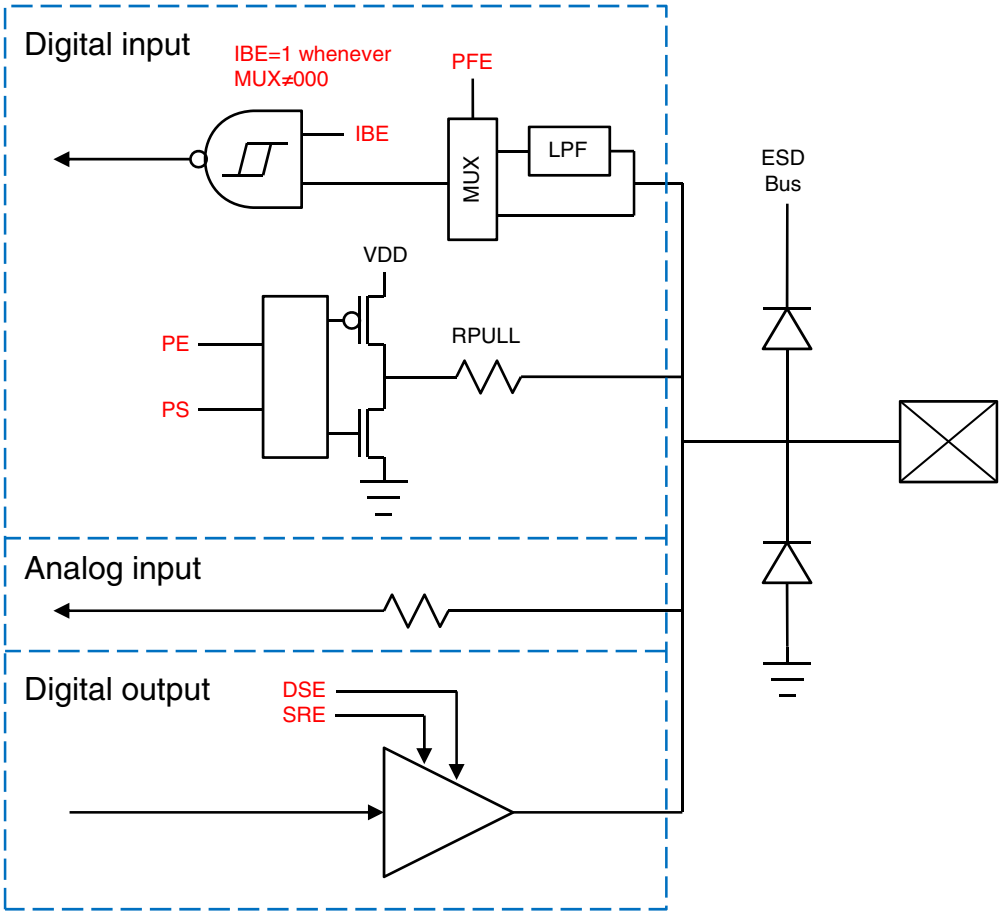


Figure 4. I/O simplified block diagram

The PORT module has the following features:

- all PIN support interrupt enable
- Configurable edge (rising, falling, or both) or level sensitive interrupt type
- Support DMA request
- Asynchronous wake-up in low-power modes
- Configurable pullup, pulldown, and pull-disable on select pins
- Configurable high and low drive strength on selected pins
- Configurable fast and slow slew rates on selected pins
- Configurable passive filter on selected pins
- Individual mux control field supporting analog or pin disabled, GPIO, and up to chip-specific digital functions
- Pad configuration fields are functional in all digital pin muxing modes.

The GPIO module has the following features:

- Port Data Input register visible in all digital pin-multiplexing modes
- Port Data Output register with corresponding set/clear/toggle registers

100 LQFP	64 LQFP	48 QFN	Pin Name	Default	ALT0	ALT1	ALT2	ALT3	ALT4	ALT5	ALT6	ALT7
51	33	25	PTA19	XTAL0	XTAL0	PTA19			TPM_CLKIN1		LPTMR0_ ALT1	
52	34	26	RESET_b	RESET_b	RESET_b							
53	35	27	PTB0/ LLWU_P5	ADC0_SE8	ADC0_SE8	PTB0/ LLWU_P5	LPI2C0_SCL	TPM1_CH0			FXIO0_D4	UART0_RX
54	36	28	PTB1	ADC0_SE9	ADC0_SE9	PTB1	LPI2C0_SDA	TPM1_CH1		EWM_IN	FXIO0_D5	UART0_TX
55	37	29	PTB2	ADC0_SE12	ADC0_SE12	PTB2	LPI2C0_SCL	UART0_ RTS_b			FXIO0_D6	CAN1_RX
56	38	30	PTB3	ADC0_SE13	ADC0_SE13	PTB3	LPI2C0_SDA	UART0_ CTS_b			FXIO0_D7	CAN1_TX
57	—	—	PTB9	DISABLED		PTB9	SPI1_PCS1	LPUART0_ CTS_b				
58	—	—	PTB10	DISABLED		PTB10	SPI1_PCS0	LPUART0_ RX	I2S1_TX_ BCLK			
59	—	—	PTB11	DISABLED		PTB11	SPI1_SCK	LPUART0_ TX	I2S1_TX_FS			
60	—	—	VSS	VSS	VSS							
61	—	—	VDD	VDD	VDD							
62	39	31	PTB16	DISABLED		PTB16	SPI1_SOUT	UART0_RX	TPM_CLKIN0		EWM_IN	I2S1_TXD0 (Note: 100LQFP only)
63	40	—	PTB17	DISABLED		PTB17	SPI1_SIN	UART0_TX	TPM_CLKIN1		EWM_OUT_b	FXIO0_D0
64	41	32	PTB18	DISABLED		PTB18	CAN0_TX	TPM2_CH0	I2S0_TX_ BCLK			FXIO0_D1
65	42	33	PTB19	DISABLED		PTB19	CAN0_RX	TPM2_CH1	I2S0_TX_FS			FXIO0_D2
66	—	—	PTB20	DISABLED		PTB20					CMP0_OUT	FXIO0_D4
67	—	—	PTB21	DISABLED		PTB21					FXIO0_D5	
68	—	—	PTB22	DISABLED		PTB22					FXIO0_D6	
69	—	—	PTB23	DISABLED		PTB23		SPI0_PCS5			FXIO0_D7	
70	43	—	PTC0	ADC0_SE14	ADC0_SE14	PTC0	SPI0_PCS4	PDB0_ EXTRG	USB_SOF_ OUT		FXIO0_D3	SPI0_PCS0
71	44	34	PTC1/ LLWU_P6	ADC0_SE15	ADC0_SE15	PTC1/ LLWU_P6	SPI0_PCS3	UART1_ RTS_b	TPM0_CH0		I2S0_TXD0	LPUART0_ RTS_b
72	45	35	PTC2	ADC0_SE4b	ADC0_SE4b	PTC2	SPI0_PCS2	UART1_ CTS_b	TPM0_CH1		I2S0_TX_FS	LPUART0_ CTS_b
73	46	36	PTC3/ LLWU_P7	DISABLED		PTC3/ LLWU_P7	SPI0_PCS1	UART1_RX	TPM0_CH2	CLKOUT	I2S0_TX_ BCLK	LPUART0_ RX
74	47	—	VSS	VSS	VSS							
75	48	—	VDD	VDD	VDD							
76	49	37	PTC4/ LLWU_P8	DISABLED		PTC4/ LLWU_P8	SPI0_PCS0	UART1_TX	TPM0_CH3		LPI2C0_ HREQ	LPUART0_ TX
77	50	38	PTC5/ LLWU_P9	DISABLED		PTC5/ LLWU_P9	SPI0_SCK	LPTMR0_ ALT2	I2S0_RXD0		CMP0_OUT	TPM0_CH2

Table 26. CAN 1 (for KS22 only) Signal Descriptions

Chip signal name	Module signal name	Description	I/O
CAN1_RX	CAN Rx	CAN Receive Pin	Input
CAN1_TX	CAN Tx	CAN Transmit Pin	Output

Table 27. SPI 0 Signal Descriptions

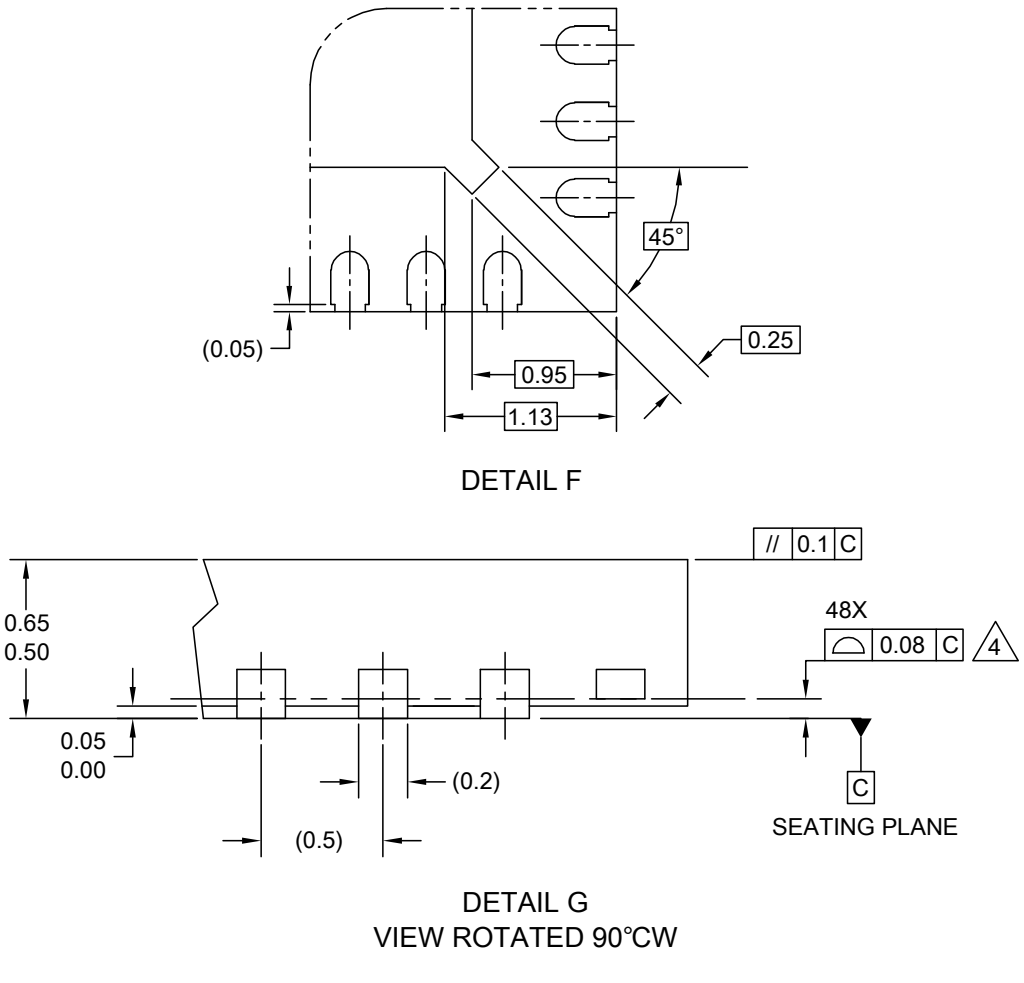
Chip signal name	Module signal name	Description	I/O
SPI0_PCS0	PCS0/$\overline{SS}$	Peripheral Chip Select 0 (O)	I/O
SPI0_PCS[3:1]	PCS[1:3]	Peripheral Chip Selects 1–3	O
SPI0_PCS4	PCS4	Peripheral Chip Select 4	O
SPI0_PCS5	PCS5/ $\overline{PCSS}$	Peripheral Chip Select 5 /Peripheral Chip Select Strobe	O
SPI0_SIN	SIN	Serial Data In	I
SPI0_SOUT	SOUT	Serial Data Out	O
SPI0_SCK	SCK	Serial Clock (O)	I/O

Table 28. SPI 1 Signal Descriptions

Chip signal name	Module signal name	Description	I/O
SPI1_PCS0	PCS0/$\overline{SS}$	Peripheral Chip Select 0 (O)	I/O
SPI1_PCS[3:1]	PCS[1:3]	Peripheral Chip Selects 1–3	O
SPI1_SIN	SIN	Serial Data In	I
SPI1_SOUT	SOUT	Serial Data Out	O
SPI1_SCK	SCK	Serial Clock (O)	I/O

Table 29. LPI^{2}C 0 Signal Descriptions

Chip signal name	Module signal name	Description	I/O
LPI2C0_SCL	SCL	LPI2C clock line.	I/O
LPI2C0_SDA	SDA	LPI2C data line.	I/O
LPI2C0_HREQ	HREQ	Host request, can initiate an LPI2C master transfer if asserted and the I2C bus is idle.	I
LPI2C0_SCLS	SCLS	Secondary I2C clock line. If LPI2C master/slave are configured to use separate pins, this the LPI2C slave SCL pin.	I/O
LPI2C0_SDAS	SDAS	Secondary I2C data line. If LPI2C master/slave are configured to use separate pins, this the LPI2C slave SDA pin.	I/O



NOTES:

1. ALL DIMENSIONS ARE IN MILLIMETERS.
2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.
3. THIS IS A NON-JEDEC REGISTERED PACKAGE.
4. COPLANARITY APPLIES TO LEADS AND DIE ATTACH FLAG.
5. MIN. METAL GAP SHOULD BE 0.2 MM.

Figure 14. 48-pin QFN package dimension 2

5 Electrical characteristics

5.1 Terminology and guidelines

Table 41. V_{DD} supply HVD, LVD and POR operating requirements (continued)

Symbol	Description	Min.	Typ.	Max.	Unit	Notes
V_{LVW1L}	• Level 1 falling (LVWV=00)	1.74	1.80	1.86	V	
V_{LVW2L}	• Level 2 falling (LVWV=01)	1.84	1.90	1.96	V	
V_{LVW3L}	• Level 3 falling (LVWV=10)	1.94	2.00	2.06	V	
V_{LVW4L}	• Level 4 falling (LVWV=11)	2.04	2.10	2.16	V	
V_{HYSL}	Low-voltage inhibit reset/recover hysteresis — low range	—	60	—	mV	
V_{BG}	Bandgap voltage reference	0.97	1.00	1.03	V	
t_{LPO}	Internal low power oscillator period — factory trimmed	900	1000	1100	µs	

1. Rising threshold is the sum of falling threshold and hysteresis voltage

Table 42. VBAT power operating requirements

Symbol	Description	Min.	Typ.	Max.	Unit	Notes
V_{POR_VBAT}	Falling VBAT supply POR detect voltage	0.8	1.1	1.5	V	

5.3.2.3 Voltage and current operating behaviors

Table 43. Voltage and current operating behaviors

Symbol	Description	Min.	Typ.	Max.	Unit	Notes
V_{OH}	Output high voltage — Normal drive pad except RESET_B					
	2.7 V ≤ V_{DD} ≤ 3.6 V, I_{OH} = -5 mA	V_{DD} – 0.5	—	—	V	1
	1.71 V ≤ V_{DD} ≤ 2.7 V, I_{OH} = -2.5 mA	V_{DD} – 0.5	—	—	V	
V_{OH}	Output high voltage — High drive pad except RESET_B					
	2.7 V ≤ V_{DD} ≤ 3.6 V, I_{OH} = -20 mA	V_{DD} – 0.5	—	—	V	1
	1.71 V ≤ V_{DD} ≤ 2.7 V, I_{OH} = -10 mA	V_{DD} – 0.5	—	—	V	
I_{OHT}	Output high current total for all ports	—	—	100	mA	
V_{OL}	Output low voltage — Normal drive pad except RESET_B					
	2.7 V ≤ V_{DD} ≤ 3.6 V, I_{OL} = 5 mA	—	—	0.5	V	1
	1.71 V ≤ V_{DD} ≤ 2.7 V, I_{OL} = 2.5 mA	—	—	0.5	V	
V_{OL}	Output low voltage — High drive pad except RESET_B					
	2.7 V ≤ V_{DD} ≤ 3.6 V, I_{OL} = 20 mA	—	—	0.5	V	1
	1.71 V ≤ V_{DD} ≤ 2.7 V, I_{OL} = 10 mA	—	—	0.5	V	
V_{OL}	Output low voltage — RESET_B					
	2.7 V ≤ V_{DD} ≤ 3.6 V, I_{OL} = 3 mA	—	—	0.5	V	

Table continues on the next page...

Table 43. Voltage and current operating behaviors (continued)

Symbol	Description	Min.	Typ.	Max.	Unit	Notes
	1.71 V ≤ V_{DD} ≤ 2.7 V, I_{OL} = 1.5 mA	—	—	0.5	V	
I_{OLT}	Output low current total for all ports	—	—	100	mA	
I_{IN}	Input leakage current (per pin) for full temperature range					
	All pins other than high drive port pins	—	0.002	0.5	µA	1, 2
	High drive port pins	—	0.004	0.5	µA	
I_{IN}	Input leakage current (total all pins) for full temperature range	—	—	1.0	µA	2
R_{PU}	Internal pullup resistors	20	—	50	kΩ	3
R_{PD}	Internal pulldown resistors	20	—	50	kΩ	4

1. PTB0, PTB1, PTD4, PTD5, PTD6, PTD7, PTC3, and PTC4 I/O have both high drive and normal drive capability selected by the associated PTx_PCRn[DSE] control bit. All other GPIOs are normal drive only.
2. Measured at VDD=3.6V
3. Measured at V_{DD} supply voltage = V_{DD} min and Vinput = V_{SS}
4. Measured at V_{DD} supply voltage = V_{DD} min and Vinput = V_{DD}

5.3.2.4 Power mode transition operating behaviors

All specifications except t_{POR} and VLLSx → RUN recovery times in the following table assume this clock configuration:

- CPU and system clocks = 80 MHz
- Bus clock = 40 MHz
- Flash clock = 20 MHz
- MCG mode: FEI

Table 44. Power mode transition operating behaviors

Symbol	Description	Min.	Typ.	Max.	Unit	Notes
t_{POR}	After a POR event, amount of time from the point V_{DD} reaches 1.71 V to execution of the first instruction across the operating temperature range of the chip.	—	—	300	µs	1
	• VLLS0 → RUN	—	—	140	µs	
	• VLLS1 → RUN	—	—	140	µs	
	• VLLS2 → RUN	—	—	80	µs	
	• VLLS3 → RUN	—	—	80	µs	

Table continues on the next page...

5.3.3.1 Device clock specifications

Table 48. Device clock specifications

Symbol	Description	Min.	Max.	Unit
High Speed run mode				
f_{SYS}	System and core clock	—	120	MHz
f_{BUS}	Bus clock	—	60	MHz
Normal run mode				
f_{SYS}	System and core clock	—	80	MHz
f_{SYS_USB}	System and core clock when Full Speed USB in operation	20	—	MHz
f_{BUS}	Bus clock	—	50	MHz
f_{FLASH}	Flash clock	—	26.67	MHz
f_{LPTMR}	LPTMR clock	—	25	MHz
VLPR and VLPS modes[1]				
f_{SYS}	System and core clock	—	4	MHz
f_{BUS}	Bus clock	—	4	MHz
f_{FLASH}	Flash clock	—	1	MHz
f_{ERCLK}	External reference clock	—	16	MHz
f_{LPTMR_pin}	LPTMR clock	—	25	MHz
f_{LPTMR_ERCLK}	LPTMR external reference clock	—	16	MHz
f_{I2S_MCLK}	I2S master clock	—	12.5	MHz
f_{I2S_BCLK}	I2S bit clock	—	4	MHz
f_{FlexIO}	FlexIO clock	—	16	MHz
f_{LPI2C}	LPI2C clock	—	16	MHz
$f_{FlexCAN}$	FlexCAN clock	—	4	MHz

1. The frequency limitations in VLPR and VLPS modes here override any frequency specification listed in the timing specification for any other module. These same frequency limits apply to VLPS, whether VLPS was entered from RUN or from VLPR.

5.3.3.2 General switching specifications

These general purpose specifications apply to all signals configured for GPIO, UART, and timers.

Table 49. General switching specifications

Symbol	Description	Min.	Max.	Unit	Notes
	GPIO pin interrupt pulse width (digital glitch filter disabled) — Synchronous path	1.5	—	Bus clock cycles	1, 2
	External RESET and NMI pin interrupt pulse width — Asynchronous path	100	—	ns	3

Table continues on the next page...

5.4.1.1 SWD electricals

Table 52. SWD full voltage range electricals

Symbol	Description	Min.	Max.	Unit
	Operating voltage	1.71	3.6	V
S1	SWD_CLK frequency of operation • Serial wire debug	 0	 33	 MHz
S2	SWD_CLK cycle period	1/S1	—	ns
S3	SWD_CLK clock pulse width • Serial wire debug	 15	 —	 ns
S4	SWD_CLK rise and fall times	—	3	ns
S9	SWD_DIO input data setup time to SWD_CLK rise	8	—	ns
S10	SWD_DIO input data hold time after SWD_CLK rise	1.4	—	ns
S11	SWD_CLK high to SWD_DIO data valid	—	25	ns
S12	SWD_CLK high to SWD_DIO high-Z	5	—	ns

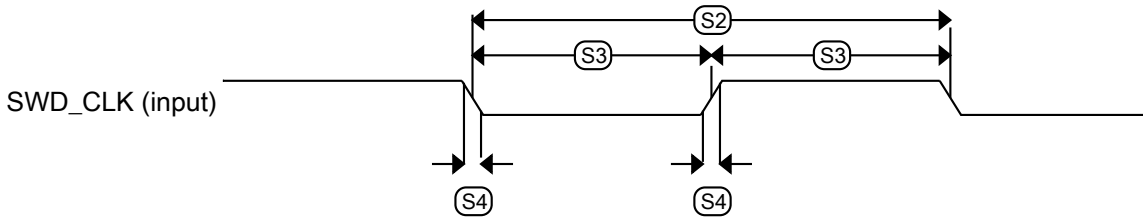


Figure 18. Serial wire clock input timing

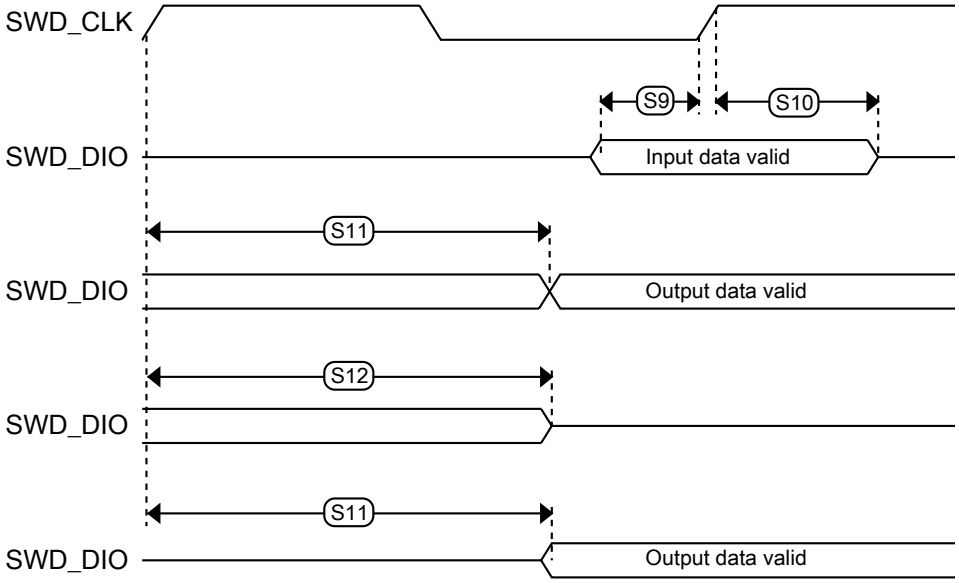


Figure 19. Serial wire data timing

5.4.1.2 JTAG electricals

Table 53. JTAG limited voltage range electricals

Symbol	Description	Min.	Max.	Unit
	Operating voltage	2.7	3.6	V
J1	TCLK frequency of operation			MHz
	• Boundary Scan	0	10	
	• JTAG and CJTAG	0	20	
J2	TCLK cycle period	1/J1	—	ns
J3	TCLK clock pulse width			
	• Boundary Scan	50	—	ns
	• JTAG and CJTAG	25	—	ns
J4	TCLK rise and fall times	—	3	ns
J5	Boundary scan input data setup time to TCLK rise	20	—	ns
J6	Boundary scan input data hold time after TCLK rise	1	—	ns
J7	TCLK low to boundary scan output data valid	—	25	ns
J8	TCLK low to boundary scan output high-Z	—	25	ns
J9	TMS, TDI input data setup time to TCLK rise	8	—	ns
J10	TMS, TDI input data hold time after TCLK rise	1	—	ns

Table continues on the next page...

Table 56. IRC48M specifications (continued)

Symbol	Description	Min.	Typ.	Max.	Unit	Notes
	Regulator enable (USB_CLK_RECOVER_IRC_EN[REG_EN]=1)	—	± 0.5	± 1.5		
Δf_{irc48m_cl}	Closed loop total deviation of IRC48M frequency over voltage and temperature	—	—	± 0.1	$\%f_{host}$	2
J_{cyc_irc48m}	Period Jitter (RMS)	—	35	150	ps	
$t_{irc48mst}$	Startup time	—	2	3	µs	3

1. The maximum value represents characterized results equivalent to the mean plus or minus three times the standard deviation (mean ± 3 sigma).
2. Closed loop operation of the IRC48M is only feasible for USB device operation; it is not usable for USB host operation. It is enabled by configuring for USB Device, selecting IRC48M as USB clock source, and enabling the clock recover function (USB_CLK_RECOVER_IRC_CTRL[CLOCK_RECOVER_EN]=1, USB_CLK_RECOVER_IRC_EN[IRC_EN]=1).
3. IRC48M startup time is defined as the time between clock enablement and clock availability for system use. Enable the clock by one of the following settings:
   - USB_CLK_RECOVER_IRC_EN[IRC_EN]=1 or
   - MCG operating in an external clocking mode and MCG_C7[OSCSEL]=10 or MCG_C5[PLLCLKEN0]=1, or
   - SIM_SOPT2[PLLFLLSEL]=11

5.4.3.3 Oscillator electrical specifications

5.4.3.3.1 Oscillator DC electrical specifications

Table 57. Oscillator DC electrical specifications

Symbol	Description	Min.	Typ.	Max.	Unit	Notes
V_{DD}	Supply voltage	1.71	—	3.6	V	
I_{DDOSC}	Supply current — low-power mode (HGO=0)					1
	• 32 kHz	—	500	—	nA	
	• 4 MHz	—	200	—	µA	
	• 8 MHz (RANGE=01)	—	300	—	µA	
	• 16 MHz	—	950	—	µA	
	• 24 MHz	—	1.2	—	mA	
	• 32 MHz	—	1.5	—	mA	
I_{DDOSC}	Supply current — high-gain mode (HGO=1)					1
	• 32 kHz	—	25	—	µA	
	• 4 MHz	—	400	—	µA	
	• 8 MHz (RANGE=01)	—	500	—	µA	
	• 16 MHz	—	2.5	—	mA	
		—	3	—	mA	

Table continues on the next page...

Table 57. Oscillator DC electrical specifications (continued)

Symbol	Description	Min.	Typ.	Max.	Unit	Notes
	• 24 MHz • 32 MHz	—	4	—	mA	
C_x	EXTAL load capacitance	—	—	—		2, 3
C_y	XTAL load capacitance	—	—	—		2, 3
R_F	Feedback resistor — low-frequency, low-power mode (HGO=0)	—	—	—	MΩ	2, 4
	Feedback resistor — low-frequency, high-gain mode (HGO=1)	—	10	—	MΩ	
	Feedback resistor — high-frequency, low-power mode (HGO=0)	—	—	—	MΩ	
	Feedback resistor — high-frequency, high-gain mode (HGO=1)	—	1	—	MΩ	
R_S	Series resistor — low-frequency, low-power mode (HGO=0)	—	—	—	kΩ	
	Series resistor — low-frequency, high-gain mode (HGO=1)	—	200	—	kΩ	
	Series resistor — high-frequency, low-power mode (HGO=0)	—	—	—	kΩ	
	Series resistor — high-frequency, high-gain mode (HGO=1)	—	0	—	kΩ	
V_{pp}[5]	Peak-to-peak amplitude of oscillation (oscillator mode) — low-frequency, low-power mode (HGO=0)	—	0.6	—	V	
	Peak-to-peak amplitude of oscillation (oscillator mode) — low-frequency, high-gain mode (HGO=1)	—	V_{DD}	—	V	
	Peak-to-peak amplitude of oscillation (oscillator mode) — high-frequency, low-power mode (HGO=0)	—	0.6	—	V	
	Peak-to-peak amplitude of oscillation (oscillator mode) — high-frequency, high-gain mode (HGO=1)	—	V_{DD}	—	V	

1. V_{DD}=3.3 V, Temperature =25 °C
2. See crystal or resonator manufacturer's recommendation
3. C_x and C_y can be provided by using either integrated capacitors or external components.
4. When low-power mode is selected, R_F is integrated and must not be attached externally.
5. The EXTAL and XTAL pins should only be connected to required oscillator components and must not be connected to any other device.

NOTE

The MCGPLLCLK meets the USB jitter and signaling rate specifications for certification with the use of an external clock/crystal for both Device and Host modes.

The MCGFLLCLK does not meet the USB jitter or signaling rate specifications for certification.

The IRC48M meets the USB jitter and signaling rate specifications for certification in Device mode when the USB clock recovery mode is enabled. It does not meet the USB signaling rate specifications for certification in Host mode operation.

5.4.8.2 DSPI switching specifications (limited voltage range)

The Deserial Serial Peripheral Interface (DSPI) provides a synchronous serial bus with master and slave operations. Many of the transfer attributes are programmable. The tables below provide DSPI timing characteristics for classic SPI timing modes. Refer to the SPI chapter of the Reference Manual for information on the modified transfer formats used for communicating with slower peripheral devices.

Table 70. Master mode DSPI timing (limited voltage range)

Num	Description	Min.	Max.	Unit	Notes
	Operating voltage	2.7	3.6	V	
	Frequency of operation	—	30	MHz	
DS1	DSPI_SCK output cycle time	2 x t_{BUS}	—	ns	
DS2	DSPI_SCK output high/low time	(t_{SCK}/2) – 2	(t_{SCK}/2) + 2	ns	
DS3	DSPI_PCS*n* valid to DSPI_SCK delay	(t_{BUS} x 2) – 2	—	ns	1
DS4	DSPI_SCK to DSPI_PCS*n* invalid delay	(t_{BUS} x 2) – 2	—	ns	2
DS5	DSPI_SCK to DSPI_SOUT valid	—	8.5	ns	
DS6	DSPI_SCK to DSPI_SOUT invalid	-2	—	ns	
DS7	DSPI_SIN to DSPI_SCK input setup	16.2	—	ns	
DS8	DSPI_SCK to DSPI_SIN input hold	0	—	ns	

1. The delay is programmable in SPIx_CTARn[PSSCK] and SPIx_CTARn[CSSCK].
2. The delay is programmable in SPIx_CTARn[PASC] and SPIx_CTARn[ASC].

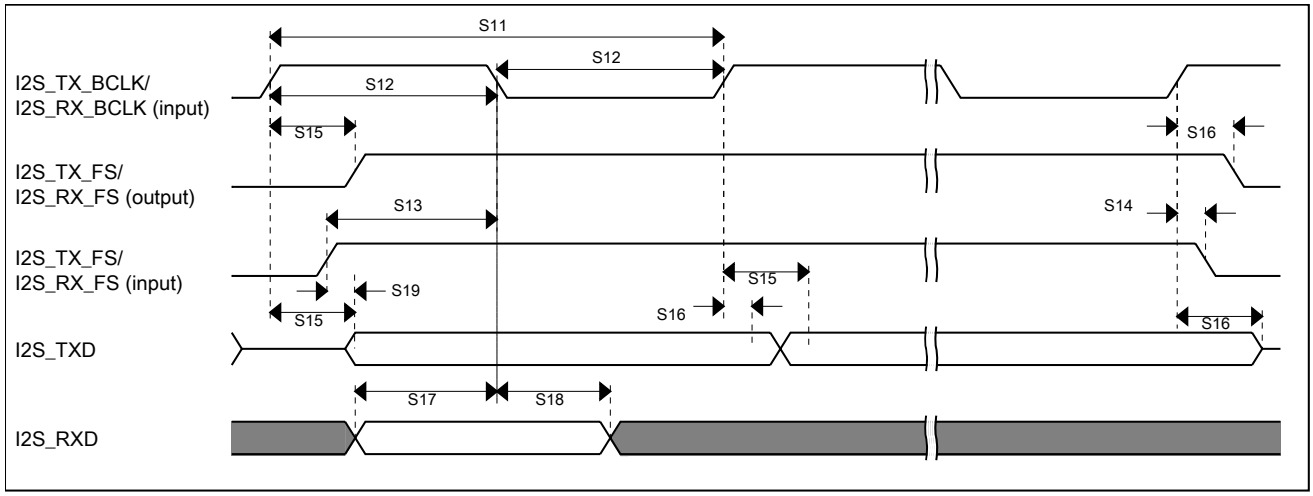


Figure 36. I2S/SAI timing — slave modes

5.4.8.6.2 Normal Run, Wait and Stop mode performance over the full operating voltage range

This section provides the operating performance over the full operating voltage for the device in Normal Run, Wait and Stop modes.

Table 77. I2S/SAI master mode timing in Normal Run, Wait and Stop modes (full voltage range)

Num.	Characteristic	Min.	Max.	Unit
	Operating voltage	1.71	3.6	V
S1	I2S_MCLK cycle time	40	—	ns
S2	I2S_MCLK pulse width high/low	45%	55%	MCLK period
S3	I2S_TX_BCLK/I2S_RX_BCLK cycle time (output)	80	—	ns
S4	I2S_TX_BCLK/I2S_RX_BCLK pulse width high/low	45%	55%	BCLK period
S5	I2S_TX_BCLK/I2S_RX_BCLK to I2S_TX_FS/ I2S_RX_FS output valid	—	15	ns
S6	I2S_TX_BCLK/I2S_RX_BCLK to I2S_TX_FS/ I2S_RX_FS output invalid	-1.0	—	ns
S7	I2S_TX_BCLK to I2S_TXD valid	—	15	ns
S8	I2S_TX_BCLK to I2S_TXD invalid	0	—	ns
S9	I2S_RXD/I2S_RX_FS input setup before I2S_RX_BCLK	27	—	ns
S10	I2S_RXD/I2S_RX_FS input hold after I2S_RX_BCLK	0	—	ns

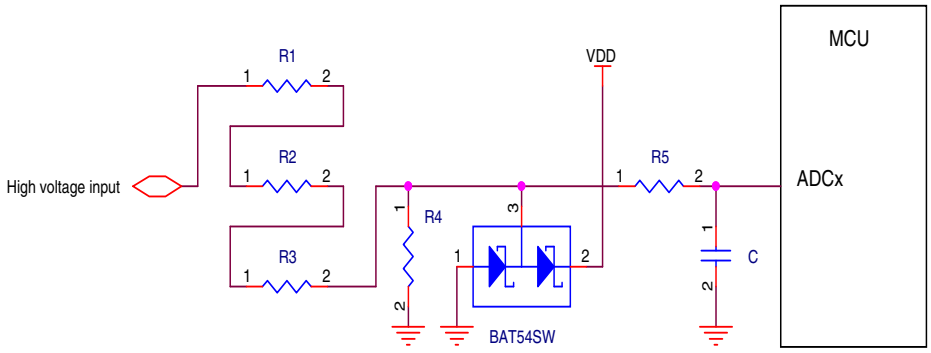


Figure 42. High voltage measurement with an ADC input

6.1.4 Digital design

Ensure that all I/O pins cannot get pulled above VDD (Max I/O is VDD+0.3V).

CAUTION

Do not provide power to I/O pins prior to VDD, especially the RESET_b pin.

- RESET_b pin

  The RESET_b pin is an open-drain I/O pin that has an internal pullup resistor. An external RC circuit is recommended to filter noise as shown in the following figure. The resistor value must be in the range of 4.7 kΩ to 10 kΩ; the recommended capacitance value is 0.1 μF. The RESET_b pin also has a selectable digital filter to reject spurious noise.

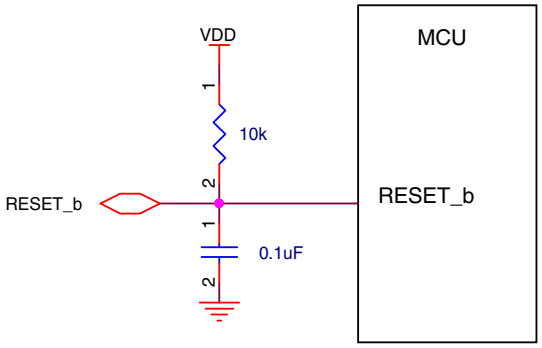


Figure 43. Reset circuit

When an external supervisor chip is connected to the RESET_b pin, a series resistor must be used to avoid damaging the supervisor chip or the RESET_b pin, as shown in the following figure. The series resistor value (RS below) must be in the range of 100 Ω to 1 kΩ depending on the external reset chip drive strength. The supervisor chip must have an active high, open-drain output.

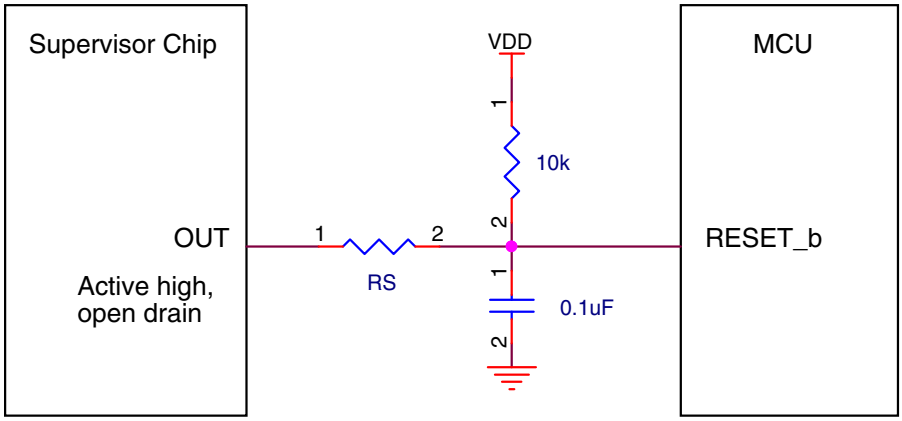


Figure 44. Reset signal connection to external reset chip

- NMI pin

  Do not add a pull-down resistor or capacitor on the NMI_b pin, because a low level on this pin will trigger non-maskable interrupt. When this pin is enabled as the NMI function, an external pull-up resistor (10 kΩ) as shown in the following figure is recommended for robustness.

  If the NMI_b pin is used as an I/O pin, the non-maskable interrupt handler is required to disable the NMI function by remapping to another function. The NMI function is disabled by programming the FOPT[NMI_DIS] bit to zero.

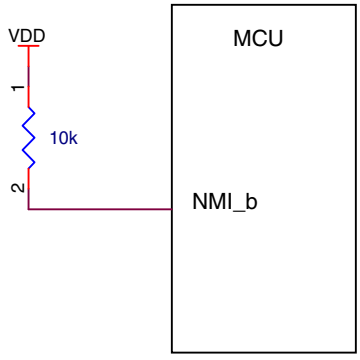


Figure 45. NMI pin biasing

- Debug interface